



# THERM-A-FORM™ CIP35 Test Report

## TR1123 December 2021 Rev. A

Chomerics Division of Parker Hannifin  
77 Dragon Court, Woburn, MA 01888  
(781) 939-4623

### **WARNING – USER RESPONSIBILITY**

**FAILURE OR IMPROPER SELECTION OR IMPROPER USE OF THE PRODUCTS DESCRIBED HEREIN OR RELATED ITEMS CAN CAUSE DEATH, PERSONAL INJURY AND PROPERTY DAMAGE.**

This document and other information from Parker-Hannifin Corporation, its subsidiaries and authorized distributors provide product or system options for further investigation by users having technical expertise.

The user, through its own analysis and testing, is solely responsible for making the final selection of the system and components and assuring that all performance, endurance, maintenance, safety and warning requirements of the application are met. The user must analyze all aspects of the application, follow applicable industry standards, and follow the information concerning the product in the current product catalog and in any other materials provided from Parker or its subsidiaries or authorized distributors. To the extent that Parker or its subsidiaries or authorized distributors provide component or system options based upon data or specifications provided by the user, the user is responsible for determining that such data and specifications are suitable and sufficient for all applications and reasonably foreseeable uses of the components or systems.

## Executive Summary

THERM-A-FORM™ CIP35 is a highly reliable, 2-component, cure-in-place, dispensable 3.5 W/m-K thermally conductive material.

This document outlines the examination of the thermal reliability of this silicone-based gap filler after being subjected to long-term environmental aging.

The thermal performance of THERM-A-FORM™ CIP35 was examined after being subjected to multiple environmental stress tests. The thermal impedance of the aged samples did not experience a significant increase after any of the treatments studied.

## **1.0 Introduction**

The purpose of the document is to explain the mechanical and environmental tests and the corresponding measurements that were performed on samples of thermally conductive gap filler THERM-A-FORM CIP35.

The samples were tested for thermal impedance and compression as a factor of pressure. The measurements were taken initially and after environmental stressing.

It is worth noting that the exact impedance value of the reliability fixture is not representative of the impedance value of the thermal interface material itself, but it can be used to measure changes to thermal performance over time.

## **2.0 Test Procedure**

### **2.1. Sample Preparation**

THERM-A-FORM CIP35 samples were prepared by dispensing from 300cc cartridges.

For the compression/deflection testing, the dispensed compounds were thickness controlled to be 0.250" with a drawbar, cut to 0.5" diameter discs, and cured at 150°C for 30 minutes before aging.

For the thermal impedance testing, the dispensed compounds were thickness controlled to 0.100" with a drawbar, cut to 1.3" diameter discs, and cured at 150°C for 30 minutes before aging.

### **2.2. Thermal Impedance Testing**

Three samples were tested at 50°C and 20 PSI (0.138 MPa) at each aging condition, per ASTM D5470.

### **2.3. Compression Deflection Testing**

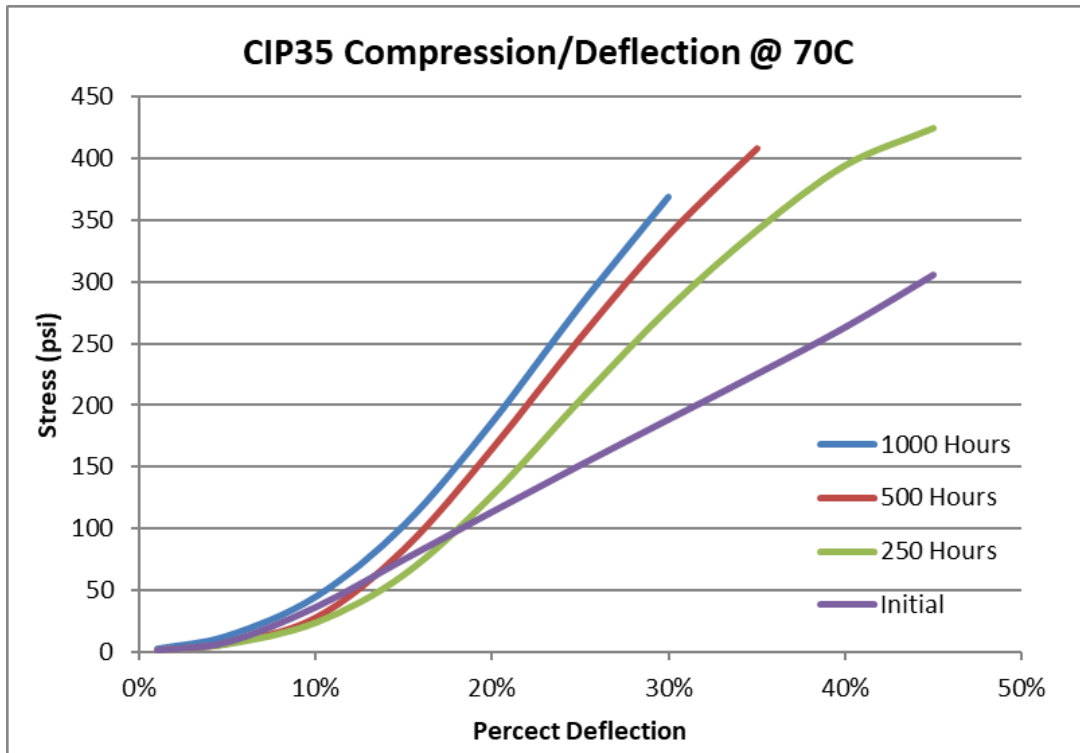
Samples were tested in a laboratory environment on a Texture Analyzer per ASTM C165. Three samples were tested at each aging condition. Samples were tested at 0.025 inches/min (0.01 mm/sec) up to 80% deflection or 50kg - the limit of the load cell.

### **2.4. NASA Outgassing**

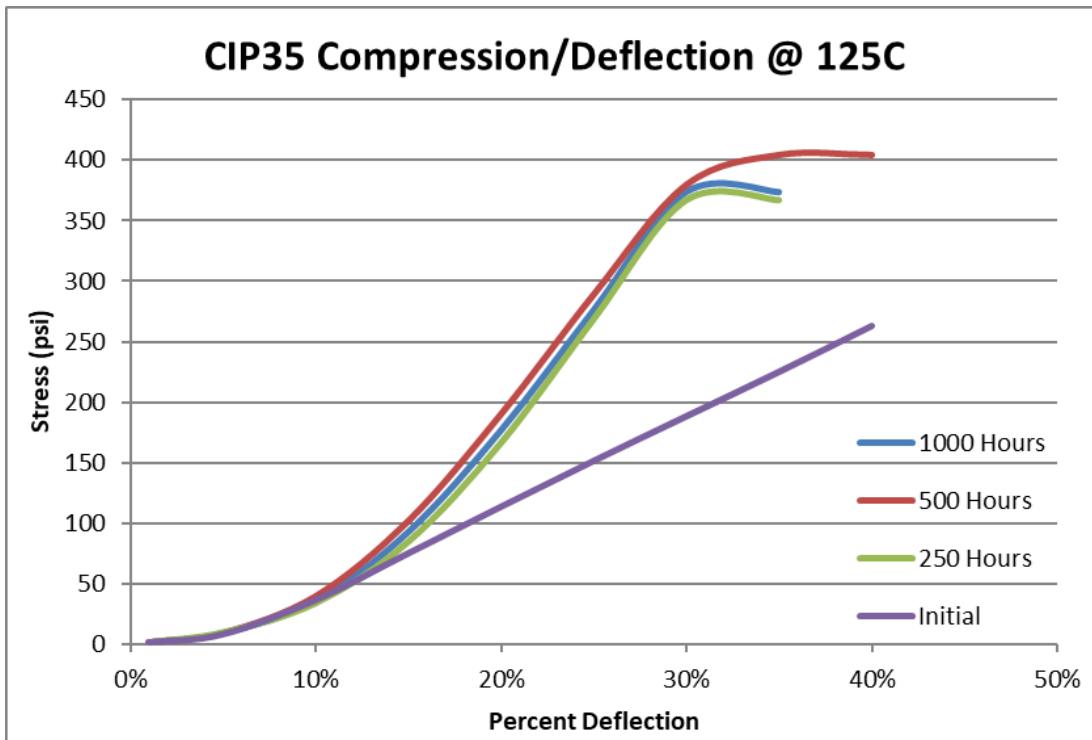
Samples were sent to an independent outside laboratory and tested for volatility analysis per ASTM E595.

### 3.0 Results

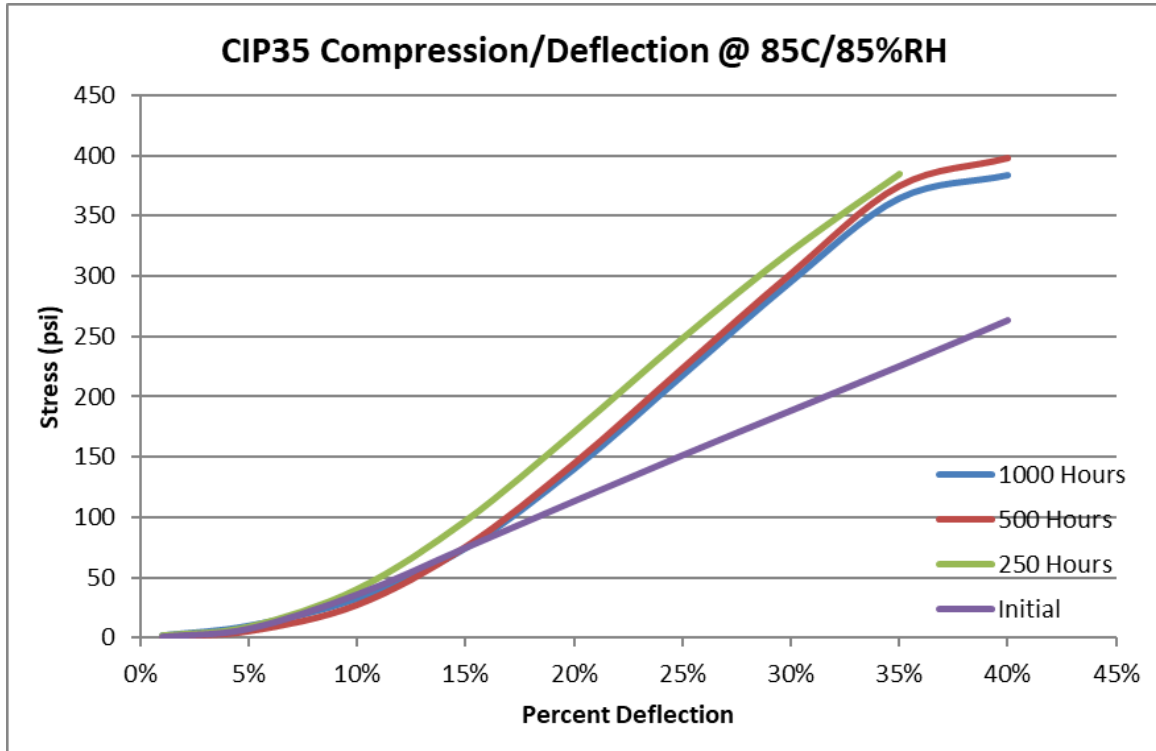
#### 3.1. Compression Deflection After Aging at 70°C: 250 mil thickness



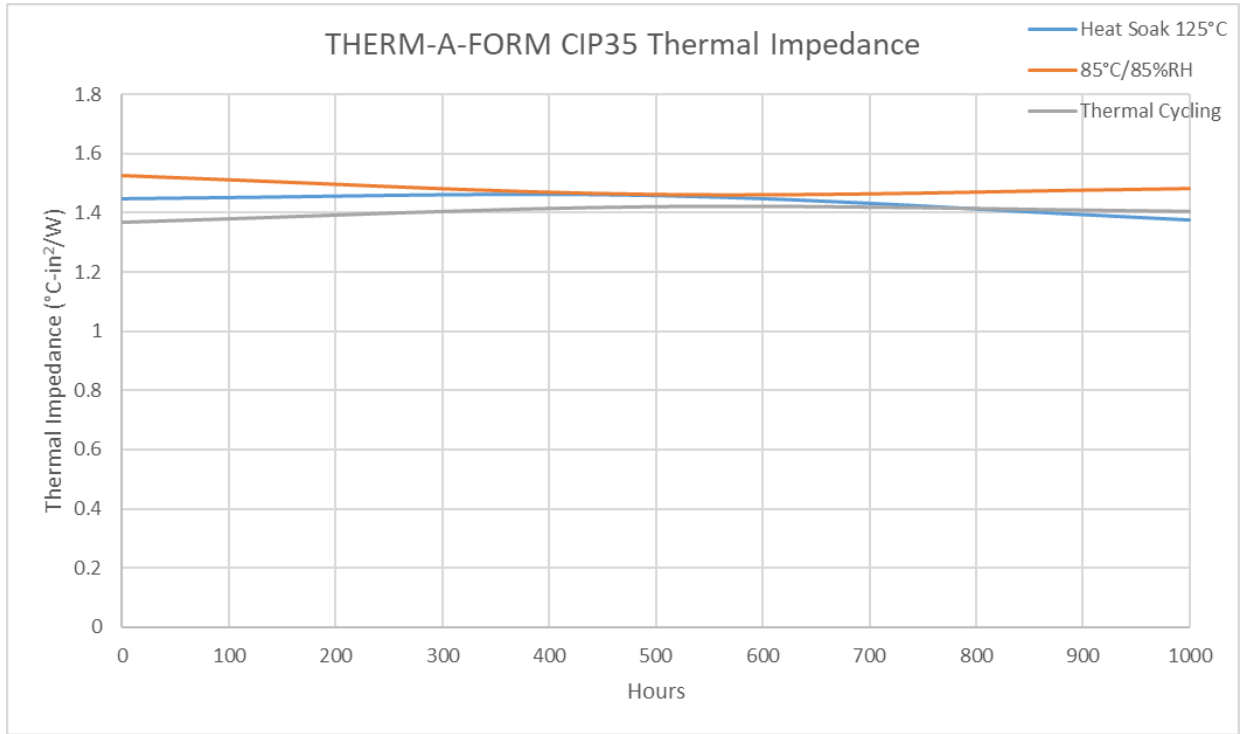
#### 3.2. Compression Deflection After Aging at 125°C: 250 mil thickness



### 3.3. Compression Deflection After Aging at 85°C/85%RH: 250 mil thickness



### 3.4. Thermal Impedance After Aging: 100 mil thickness



Environment	Initial TI (°C-in <sup>2</sup> /W)	500 Hours TI (°C-in <sup>2</sup> /W)	% Change from Initial	1000 Hours TI (°C-in <sup>2</sup> /W)	% Change from Initial
Heat Soak 125°C	1.45	1.46	1%	1.38	-5%
85°C/85%RH	1.53	1.46	-4%	1.48	-3%
Thermal Cycling	1.37	1.42	4%	1.41	3%

### 3.5. NASA Outgassing

The National Aeronautics & Space Administration (NASA) criteria for low-volatility materials limits the total mass loss (TML) to 1.0% and collected volatile condensable material (CVCM) to 0.10%.

Outgassing Results	
% Total mass loss	0.22
% CVCM	0.06

#### **4.0 Conclusion**

To summarize the above results, THERM-A-FORM™ CIP35 is highly reliable after long-term aging in multiple environments.

The mean impedance values after heat soak and heat and humidity aging saw a decrease of 5% and 3%, respectively - indicating an improvement in thermal performance. For thermal cycling aging, there was a minor increase of 3%.

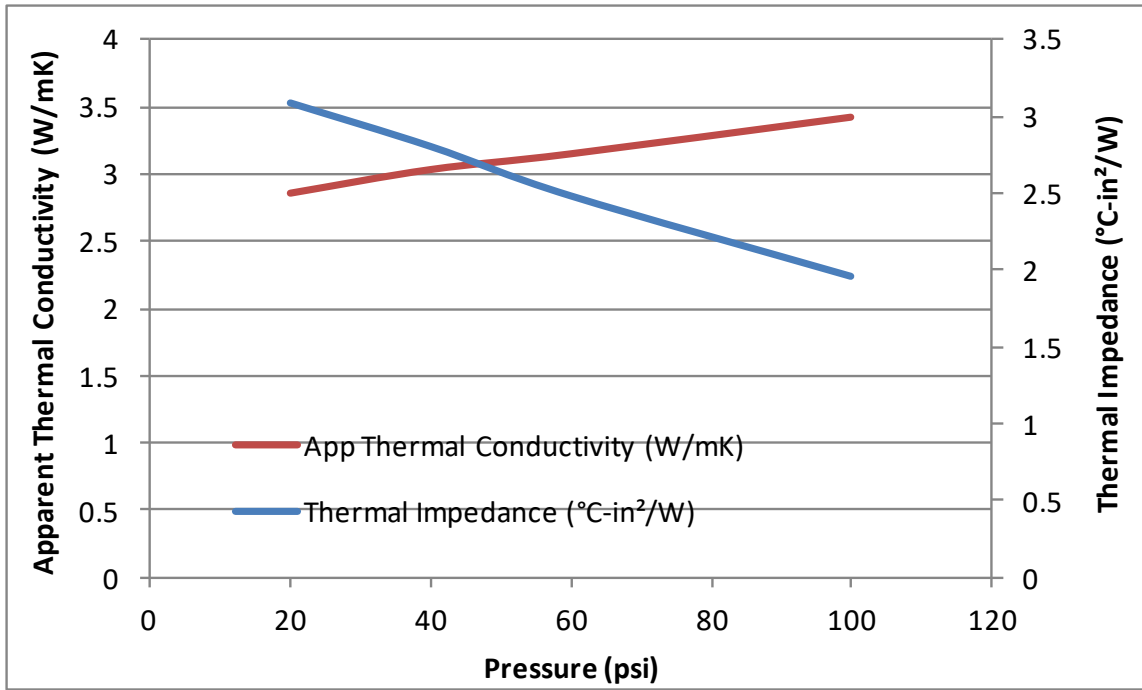
The compression/deflection curves saw minimal increases, within the recommended compression range, after experiencing heat soak, heat and humidity, and thermal cycling aging.

In addition, CIP35's outgassing results of 0.22% and 0.06% for TML and CVCM, respectively, pass the NASA outgassing criteria for low-volatility materials.

The results of this study provide evidence that CIP35 maintains reliability after long-term aging.

## Appendix: Thermal Properties vs. Pressure

250 mil CIP-250



20 mil CIP-250

